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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	288
Number of Logic Elements/Cells	4608
Total RAM Bits	119808
Number of I/O	89
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c5t144c8n

Chapter 14. IEEE 1149.1 (JTAG) Boundary-Scan Testing for Cyclone II Devices

A LAB-wide asynchronous load signal to control the logic for the register's preset signal is not available. The register preset is achieved by using a NOT gate push-back technique. Cyclone II devices can only support either a preset or asynchronous clear signal.

In addition to the clear port, Cyclone II devices provide a chip-wide reset pin (DEV_CLRn) that resets all registers in the device. An option set before compilation in the Quartus II software controls this pin. This chip-wide reset overrides all other control signals.

MultiTrack Interconnect

In the Cyclone II architecture, connections between LEs, M4K memory blocks, embedded multipliers, and device I/O pins are provided by the MultiTrack interconnect structure with DirectDrive™ technology. The MultiTrack interconnect consists of continuous, performance-optimized routing lines of different speeds used for inter- and intra-design block connectivity. The Quartus II Compiler automatically places critical paths on faster interconnects to improve design performance.

DirectDrive technology is a deterministic routing technology that ensures identical routing resource usage for any function regardless of placement within the device. The MultiTrack interconnect and DirectDrive technology simplify the integration stage of block-based designing by eliminating the re-optimization cycles that typically follow design changes and additions.

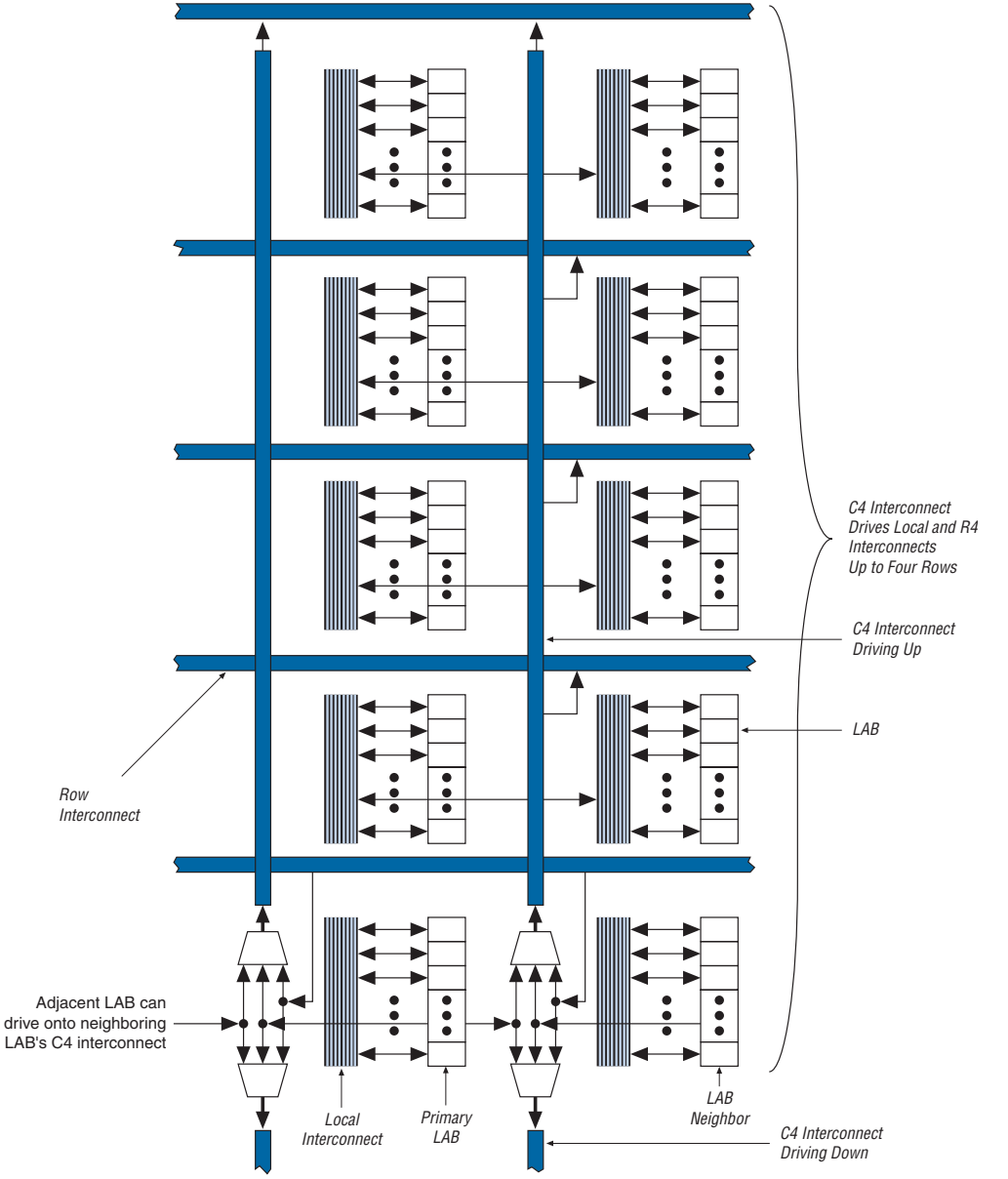
The MultiTrack interconnect consists of row (direct link, R4, and R24) and column (register chain, C4, and C16) interconnects that span fixed distances. A routing structure with fixed-length resources for all devices allows predictable and repeatable performance when migrating through different device densities.

Row Interconnects

Dedicated row interconnects route signals to and from LABs, PLLs, M4K memory blocks, and embedded multipliers within the same row. These row resources include:

- Direct link interconnects between LABs and adjacent blocks
- R4 interconnects traversing four blocks to the right or left
- R24 interconnects for high-speed access across the length of the device

Figure 2–10. C4 Interconnect Connections *Note (1)*



Note to Figure 2–10:
(1) Each C4 interconnect can drive either up or down four rows.

Embedded Multiplier Routing Interface

The R4, C4, and direct link interconnects from adjacent LABs drive the embedded multiplier row interface interconnect. The embedded multipliers can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 16 direct link input connections to the embedded multiplier are possible from the left adjacent LABs and another 16 possible from the right adjacent LAB. Embedded multiplier outputs can also connect to left and right LABs through 18 direct link interconnects each. Figure 2–19 shows the embedded multiplier to logic array interface.

Figure 2–19. Embedded Multiplier LAB Row Interface

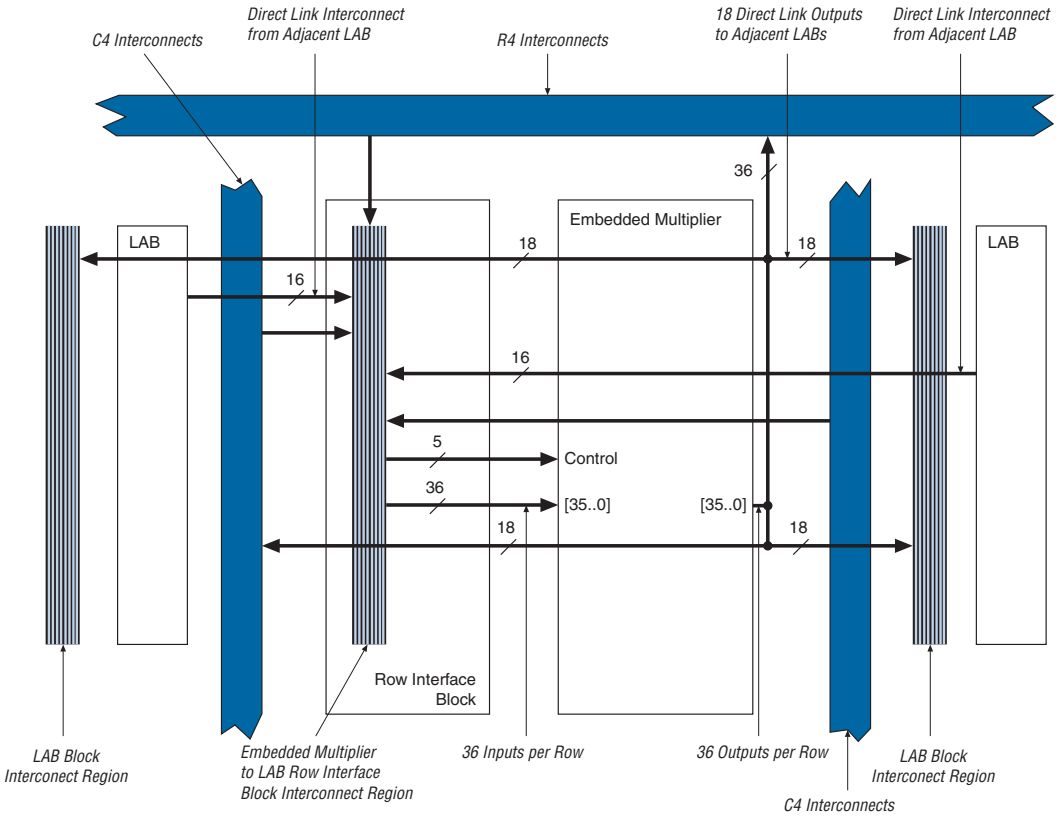
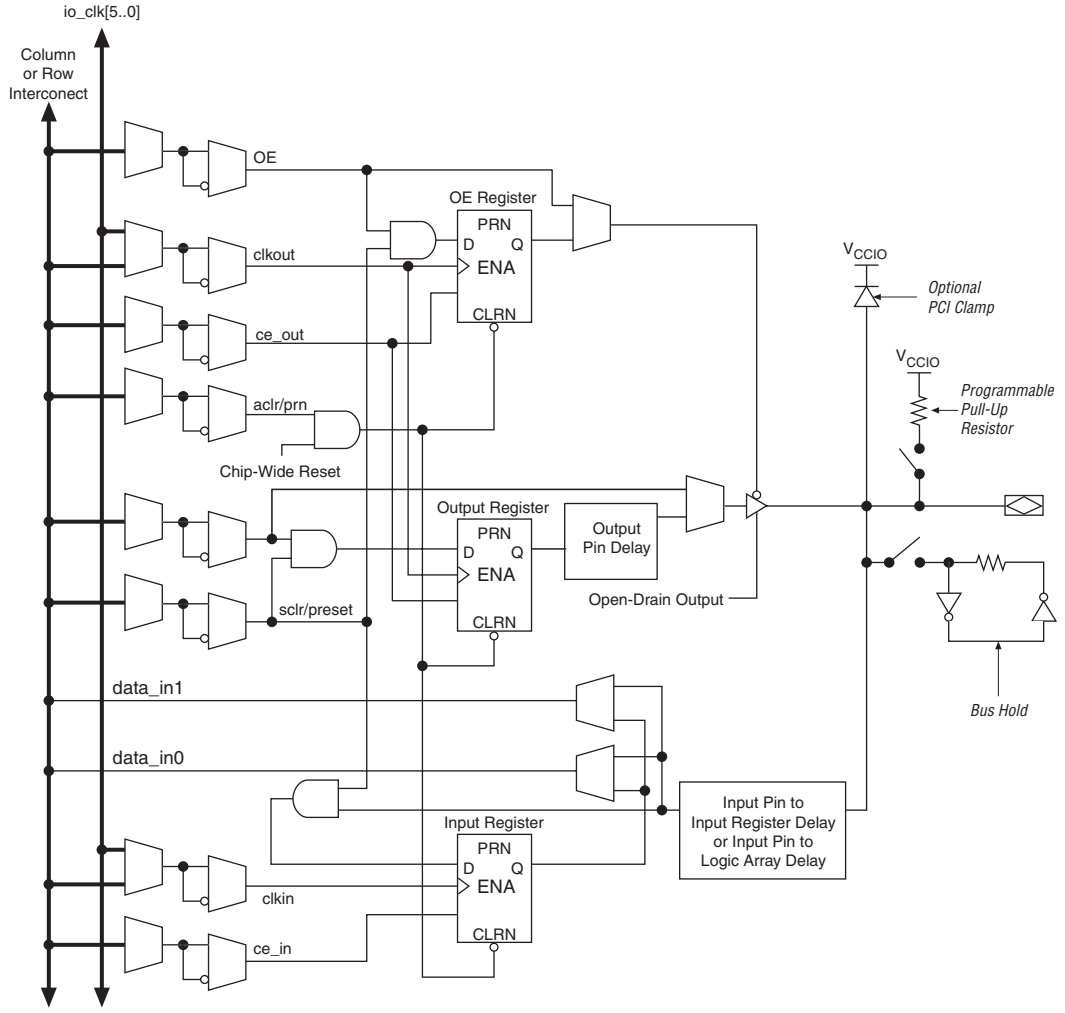


Figure 2–25. Cyclone II IOE in Bidirectional I/O Configuration



The Cyclone II device IOE includes programmable delays to ensure zero hold times, minimize setup times, or increase clock to output times.

A path in which a pin directly drives a register may require a programmable delay to ensure zero hold time, whereas a path in which a pin drives a register through combinational logic may not require the delay. Programmable delays decrease input-pin-to-logic-array and IOE input register delays. The Quartus II Compiler can program these delays to automatically minimize setup time while providing a zero hold time.

Table 2–15. Cyclone II DQS & DQ Bus Mode Support (Part 2 of 2) *Note (1)*

Device	Package	Number of ×8 Groups	Number of ×9 Groups *(5)*, *(6)*	Number of ×16 Groups	Number of ×18 Groups *(5)*, *(6)*
EP2C35	484-pin FineLine BGA	16 *(4)*	8	8	8
	672-pin FineLine BGA	20 *(4)*	8	8	8
EP2C50	484-pin FineLine BGA	16 *(4)*	8	8	8
	672-pin FineLine BGA	20 *(4)*	8	8	8
EP2C70	672-pin FineLine BGA	20 *(4)*	8	8	8
	896-pin FineLine BGA	20 *(4)*	8	8	8

Notes to Table 2–15:

(1) Numbers are preliminary.
(2) EP2C5 and EP2C8 devices in the 144-pin TQFP package do not have any DQ pin groups in I/O bank 1.
(3) Because of available clock resources, only a total of 6 DQ/DQS groups can be implemented.
(4) Because of available clock resources, only a total of 14 DQ/DQS groups can be implemented.
(5) The ×9 DQS/DQ groups are also used as ×8 DQS/DQ groups. The ×18 DQS/DQ groups are also used as ×16 DQS/DQ groups.
(6) For QDRI implementation, if you connect the D ports (write data) to the Cyclone II DQ pins, the total available ×9 DQS /DQ and ×18 DQS/DQ groups are half of that shown in Table 2–15.

You can use any of the DQ pins for the parity pins in Cyclone II devices. The Cyclone II device family supports parity in the ×8/×9, and ×16/×18 mode. There is one parity bit available per eight bits of data pins.

The data mask, DM, pins are required when writing to DDR SDRAM and DDR2 SDRAM devices. A low signal on the DM pin indicates that the write is valid. If the DM signal is high, the memory masks the DQ signals. In Cyclone II devices, the DM pins are assigned and are the preferred pins. Each group of DQS and DQ signals requires a DM pin.

When using the Cyclone II I/O banks to interface with the DDR memory, at least one PLL with two clock outputs is needed to generate the system and write clock. The system clock is used to clock the DQS write signals, commands, and addresses. The write clock is shifted by –90° from the system clock and is used to clock the DQ signals during writes.

Figure 2–27 illustrates DDR SDRAM interfacing from the I/O through the dedicated circuitry to the logic array.

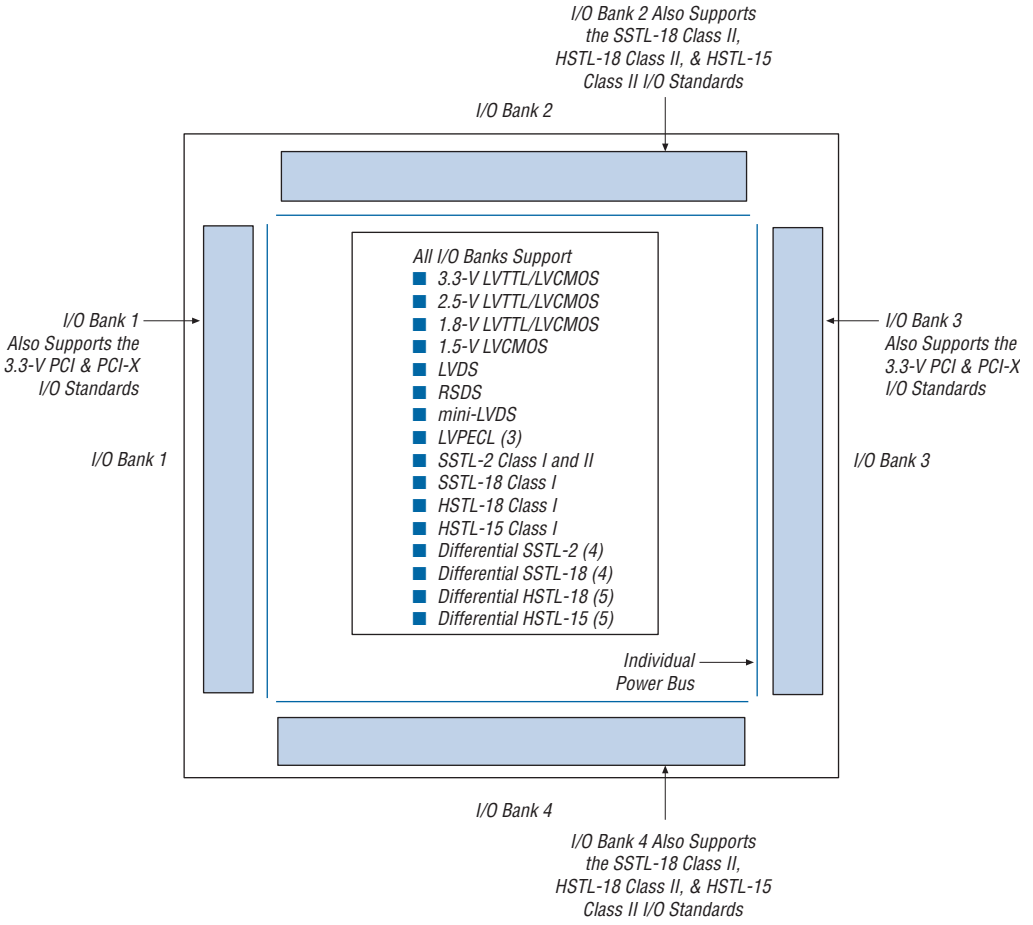
Programmable Drive Strength

The output buffer for each Cyclone II device I/O pin has a programmable drive strength control for certain I/O standards. The LVTTL, LVCMOS, SSTL-2 class I and II, SSTL-18 class I and II, HSTL-18 class I and II, and HSTL-1.5 class I and II standards have several levels of drive strength that you can control. Using minimum settings provides signal slew rate control to reduce system noise and signal overshoot. Table 2–16 shows the possible settings for the I/O standards with drive strength control.

Table 2–16. Programmable Drive Strength (Part 1 of 2) *Note (1)*

I/O Standard	I_{OH}/I_{OL} Current Strength Setting (mA)	
	Top & Bottom I/O Pins	Side I/O Pins
LVTTL (3.3 V)	4	4
	8	8
	12	12
	16	16
	20	20
	24	24
LVCMOS (3.3 V)	4	4
	8	8
	12	12
	16	
	20	
	24	
LVTTL/LVCMOS (2.5 V)	4	4
	8	8
	12	
	16	
LVTTL/LVCMOS (1.8 V)	2	2
	4	4
	6	6
	8	8
	10	10
	12	12

Figure 2–28. EP2C5 & EP2C8 I/O Banks *Notes (1), (2)*



Notes to Figure 2–28:

(1) This is a top view of the silicon die.
(2) This is a graphic representation only. Refer to the pin list and the Quartus II software for exact pin locations.
(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.
(4) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.
(5) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

Table 5–11 specifies the bus hold parameters for general I/O pins.

Table 5–11. Bus Hold Parameters *Note (1)*

Parameter	Conditions	V_{CCIO} Level						Unit
		1.8 V		2.5 V		3.3 V		
		Min	Max	Min	Max	Min	Max	
Bus-hold low, sustaining current	$V_{IN} > V_{IL}$(maximum)	30	—	50	—	70	—	µA
Bus-hold high, sustaining current	$V_{IN} < V_{IL}$(minimum)	–30	—	–50	—	–70	—	µA
Bus-hold low, overdrive current	$0 V < V_{IN} < V_{CCIO}$	—	200	—	300	—	500	µA
Bus-hold high, overdrive current	$0 V < V_{IN} < V_{CCIO}$	—	–200	—	–300	—	–500	µA
Bus-hold trip point *(2)*	—	0.68	1.07	0.7	1.7	0.8	2.0	V

Notes to Table 5–11:
(1) There is no specification for bus-hold at V_{CCIO} = 1.5 V for the HSTL I/O standard.
(2) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

On-Chip Termination Specifications

Table 5–12 defines the specifications for internal termination resistance tolerance when using series or differential on-chip termination.

Table 5–12. Series On-Chip Termination Specifications

Symbol	Description	Conditions	Resistance Tolerance			
			Commercial Max	Industrial Max	Extended/ Automotive Temp Max	Unit
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.3V	±30	±30	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 2.5V	±30	±30	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.8V	±30 *(1)*	±40	±50	%

Note to Table 5–12:
(1) For commercial –8 devices, the tolerance is ±40%.

Table 5–42. Cyclone II I/O Output Delay for Column Pins (Part 1 of 6)

I/O Standard	Drive Strength	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (2)	–7 Speed Grade (3)	–8 Speed Grade	Unit
			Industrial/ Automotive	Commer -cial					
LVTTL	4 mA	t_{OP}	1524	1599	2903	3125	3341	3348	ps
		t_{DIP}	1656	1738	3073	3319	3567	3567	ps
	8 mA	t_{OP}	1343	1409	2670	2866	3054	3061	ps
		t_{DIP}	1475	1548	2840	3060	3280	3280	ps
	12 mA	t_{OP}	1287	1350	2547	2735	2917	2924	ps
		t_{DIP}	1419	1489	2717	2929	3143	3143	ps
	16 mA	t_{OP}	1239	1299	2478	2665	2844	2851	ps
		t_{DIP}	1371	1438	2648	2859	3070	3070	ps
	20 mA	t_{OP}	1228	1288	2456	2641	2820	2827	ps
		t_{DIP}	1360	1427	2626	2835	3046	3046	ps
	24 mA (1)	t_{OP}	1220	1279	2452	2637	2815	2822	ps
		t_{DIP}	1352	1418	2622	2831	3041	3041	ps
LVCMOS	4 mA	t_{OP}	1346	1412	2509	2695	2873	2880	ps
		t_{DIP}	1478	1551	2679	2889	3099	3099	ps
	8 mA	t_{OP}	1240	1300	2473	2660	2840	2847	ps
		t_{DIP}	1372	1439	2643	2854	3066	3066	ps
	12 mA	t_{OP}	1221	1280	2428	2613	2790	2797	ps
		t_{DIP}	1353	1419	2598	2807	3016	3016	ps
	16 mA	t_{OP}	1203	1262	2403	2587	2765	2772	ps
		t_{DIP}	1335	1401	2573	2781	2991	2991	ps
	20 mA	t_{OP}	1194	1252	2378	2562	2738	2745	ps
		t_{DIP}	1326	1391	2548	2756	2964	2964	ps
	24 mA (1)	t_{OP}	1192	1250	2382	2566	2742	2749	ps
		t_{DIP}	1324	1389	2552	2760	2968	2968	ps

Table 5–43. Cyclone II I/O Output Delay for Row Pins (Part 2 of 4)

I/O Standard	Drive Strength	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (2)	–7 Speed Grade (3)	–8 Speed Grade	Unit
			Industrial /Auto-motive	Commer-cial					
1.8V	2 mA	t_{OP}	1503	1576	3657	3927	4190	4196	ps
		t_{DIP}	1627	1708	3865	4164	4463	4463	ps
	4 mA	t_{OP}	1400	1468	3010	3226	3434	3440	ps
		t_{DIP}	1524	1600	3218	3463	3707	3707	ps
	6 mA	t_{OP}	1388	1455	2857	3050	3236	3242	ps
		t_{DIP}	1512	1587	3065	3287	3509	3509	ps
	8 mA	t_{OP}	1347	1412	2714	2897	3072	3078	ps
		t_{DIP}	1471	1544	2922	3134	3345	3345	ps
	10 mA	t_{OP}	1347	1412	2714	2897	3072	3078	ps
		t_{DIP}	1471	1544	2922	3134	3345	3345	ps
	12 mA (1)	t_{OP}	1332	1396	2678	2856	3028	3034	ps
		t_{DIP}	1456	1528	2886	3093	3301	3301	ps
1.5V	2 mA	t_{OP}	1853	1943	4127	4492	4849	4855	ps
		t_{DIP}	1977	2075	4335	4729	5122	5122	ps
	4 mA	t_{OP}	1694	1776	3452	3747	4036	4042	ps
		t_{DIP}	1818	1908	3660	3984	4309	4309	ps
	6 mA (1)	t_{OP}	1694	1776	3452	3747	4036	4042	ps
		t_{DIP}	1818	1908	3660	3984	4309	4309	ps
SSTL_2_ CLASS_I	8 mA	t_{OP}	1090	1142	2152	2268	2376	2382	ps
		t_{DIP}	1214	1274	2360	2505	2649	2649	ps
	12 mA (1)	t_{OP}	1097	1150	2131	2246	2354	2360	ps
		t_{DIP}	1221	1282	2339	2483	2627	2627	ps
SSTL_2_ CLASS_II	16 mA (1)	t_{OP}	1068	1119	2067	2177	2281	2287	ps
		t_{DIP}	1192	1251	2275	2414	2554	2554	ps
SSTL_18_ CLASS_I	6 mA	t_{OP}	1371	1437	2828	3018	3200	3206	ps
		t_{DIP}	1495	1569	3036	3255	3473	3473	ps
	8 mA	t_{OP}	1365	1431	2832	3024	3209	3215	ps
		t_{DIP}	1489	1563	3040	3261	3482	3482	ps
	10 mA (1)	t_{OP}	1374	1440	2806	2990	3167	3173	ps
		t_{DIP}	1498	1572	3014	3227	3440	3440	ps

Table 7–6. I/O Standards Supported for Cyclone II PLLs (Part 2 of 2)

I/O Standard	Input	Output	
	inclk	lock	pll_out
SSTL-25 class II	✓	✓	✓
RSDS/mini-LVDS *(4)*		✓	✓

Notes to Table 7–6:
(1) The PCI-X I/O standard is supported only on side I/O pins.
(2) Differential SSTL and HSTL outputs are only supported on the PLL<#>_OUT pins.
(3) These I/O standards are only supported on top and bottom I/O pins.
(4) The RSDS and mini-LVDS pins are only supported on output pins.

Clock Feedback Modes

Cyclone II PLLs support four clock feedback modes: normal mode, zero delay buffer mode, no compensation mode, and source synchronous mode. Cyclone II PLLs do not have support for external feedback mode. All the supported clock feedback modes allow for multiplication and division, phase shifting, and programmable duty cycle. The phase relationships shown in the waveforms in Figures 7–4 through 7–6 are for the default (zero degree) phase shift setting. Changing the phase-shift setting changes the relationships between the output clocks from the PLL.

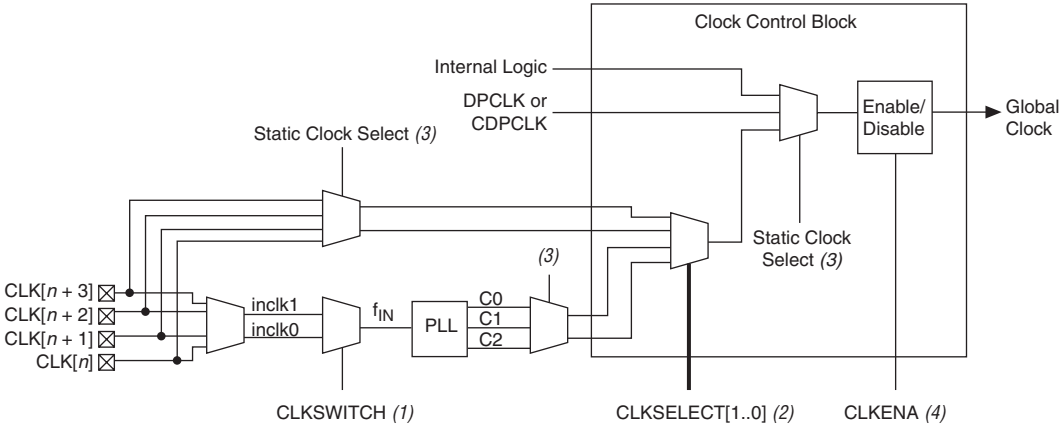
Normal Mode

In normal mode, the PLL phase-aligns the input reference clock with the clock signal at the ports of the registers in the logic array I/O registers to compensate for the internal global clock network delay. Use the `altpll` megafunction in the Quartus II software to define which internal clock output from the PLL (c0, c1, or c2) to compensate for.

If an external clock output pin (PLL<#>_OUT) is used in this mode, there is a phase shift with respect to the clock input pin. Similarly, if the internal PLL clock outputs are used to drive general-purpose I/O pins, there is be phase shift with respect to the clock input pin.

Figure 7–4 shows an example waveform of the PLL clocks' phase relationship in this mode.

Figure 7–11. Clock Control Block



Notes to Figure 7–11:

(1) The `CLKSWITCH` signal can either be set through the configuration file or dynamically set when using the manual PLL switchover feature. The output of the multiplexer is the input reference clock (f_{IN}) for the PLL.

(2) The `CLKSELECT[1..0]` signals are fed by internal logic and can be used to dynamically select the clock source for the global clock network when the device is in user mode.

(3) The static clock select signals are set in the configuration file and cannot be dynamically controlled when the device is in user mode.

(4) Internal logic can be used to enable or disable the global clock network in user mode.

Each PLL generates three clock outputs through the `c[1..0]` and c2 counters. Two of these clocks can drive the global clock network through the clock control block.

Global Clock Network Clock Source Generation

There are a total of 8 clock control blocks on the smaller Cyclone II devices (EP2C5 and EP2C8 devices) and a total of 16 clock control blocks on the larger Cyclone II devices (EP2C15 devices and larger). Figure 7–12 shows the Cyclone II clock inputs and the clock control blocks placement.

QDRII SRAM devices use the following clock signals:

- Input clocks K and K#
- Optional output clocks C and C#
- Echo clocks CQ and CQn

Clocks C#, K#, and CQn are logical complements of clocks C, K, and CQ, respectively. Clocks C, C#, K, and K# are inputs to the QDRII SRAM, and clocks CQ and CQn are outputs from the QDRII SRAM. Cyclone II devices use single-clock mode for QDRII SRAM interfacing. The K and K# clocks are used for both read and write operations, and the C and C# clocks are unused.

You can generate C, C#, K, and K# clocks using any of the I/O registers via the DDR registers. Due to strict skew requirements between K and K# signals, use adjacent pins to generate the clock pair. Surround the pair with buffer pins tied to V_{CC} and pins tied to ground for better noise immunity from other signals.

In Cyclone II devices, another DQS pin implements the CQn pin in the QDRII SRAM memory interface. These pins are denoted by DQS/CQ# in the pin table. Connect CQ and CQn pins to the Cyclone II DQS/CQ and DQS/CQ# pins of the same DQ groups, respectively. You must configure the DQS/CQ and DQS/CQ# as bidirectional pins. However, because CQ and CQn pins are output-only pins from the memory device, the Cyclone II device's QDRII SRAM memory interface requires that you ground the DQS/CQ and DQS/CQ# output enable. To capture data presented by the memory device, connect the shifted CQ signal to register C_I and input register A_I. Connect the shifted CQn to input register B_I. Figure 9–4 shows the CQ and CQn connections for a QDRII SRAM read.

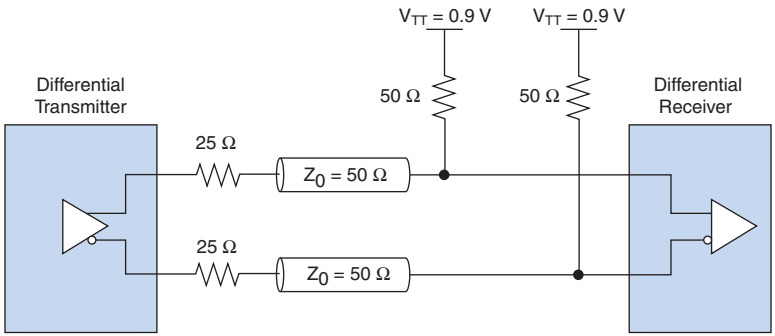
Pseudo-Differential SSTL-18 Class I and Differential SSTL-18 Class II

The 1.8-V differential SSTL-18 standard is formulated under JEDEC Standard, JESD8-15: Stub Series Terminated Logic for 1.8V (SSTL-18).

The differential SSTL-18 I/O standard is a 1.8-V standard used for applications such as high-speed DDR2 SDRAM interfaces. This standard supports differential signals in systems using the SSTL-18 standard and supplements the SSTL-18 standard for differential clocks. Refer to Figures 10–9 and 10–10 for details on differential SSTL-18 termination.

Cyclone II devices do not support true differential SSTL-18 standards. Cyclone II devices support pseudo-differential SSTL-18 outputs for `PLL_OUT` pins and pseudo-differential SSTL-18 inputs for clock pins. Pseudo-differential inputs require an input reference voltage as opposed to the true differential inputs. Refer to Table 10–1 on page 10–2 for information about pseudo-differential SSTL.

Figure 10–9. Differential SSTL-18 Class I Termination



pin+11
$\Sigma I_{PIN} < 240mA$ per power pair
pin

In all cases listed above, the Quartus II software generates an error message for illegally placed pads.

Table 10–12 shows the I/O standard DC current specification.

Table 10–12. Cyclone II I/O Standard DC Current Specification (Preliminary) (Part 1 of 2)

I/O Standard	I_{PIN} (mA)	
	Top and Bottom Banks	Side Banks
LVTTL	*(1)*	*(1)*
LVCMOS	*(1)*	*(1)*
2.5 V	*(1)*	*(1)*
1.8 V	*(1)*	*(1)*
1.5 V	*(1)*	*(1)*
3.3-V PCI	Not supported	1.5
3.3-V PCI-X	Not supported	1.5
SSTL-2 class I	12 *(2)*	12 *(2)*
SSTL-2 class II	24 *(2)*	20 *(2)*
SSTL-18 class I	12 *(2)*	12 *(2)*
SSTL-18 class II	8 *(2)*	Not supported
1.8-V HSTL class I	12 *(2)*	12 *(2)*
1.8-V HSTL class II	20 *(2)*	Not supported
1.5-V HSTL class I	12 *(2)*	10 *(2)*
1.5-V HSTL class II	18 *(2)*	Not supported
Differential SSTL-2 class I *(3)*	8.1 *(4)*	
Differential SSTL-2 class II *(3)*	16.4 *(4)*	
Differential SSTL-18 class I *(3)*	6.7 *(4)*	
Differential SSTL-18 class II *(3)*	13.4 *(4)*	
1.8-V differential HSTL class I *(3)*	8 *(4)*	
1.8-V differential HSTL class II *(3)*	16 *(4)*	
1.5-V differential HSTL class I *(3)*	8 *(4)*	

Table 11–1. LVDS I/O Specifications (Part 2 of 2) *Note (1)*

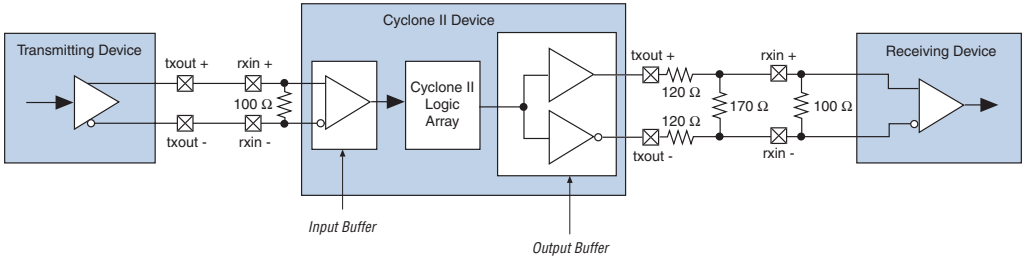
Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{ID}	Input differential voltage (single-ended)		0.1		0.65	V
V_{ICM}	Input common mode voltage		0.1		2.0	V
ΔV_{OS}	Change in V_{OS} between H and L	R_L = 100 Ω			50	mV
R_L	Receiver differential input resistor		90	100	110	Ω

Note to Table 11–1:
(1) The specifications apply at the resistor network output.

LVDS Receiver & Transmitter

Figure 11–3 shows a simple point-to-point LVDS application where the source of the data is an LVDS transmitter. These LVDS signals are typically transmitted over a pair of printed circuit board (PCB) traces, but a combination of a PCB trace, connectors, and cables is a common application setup.

Figure 11–3. Typical LVDS Application



Figures 11–4 and 11–5 show the signaling levels for LVDS receiver inputs and transmitter outputs, respectively.

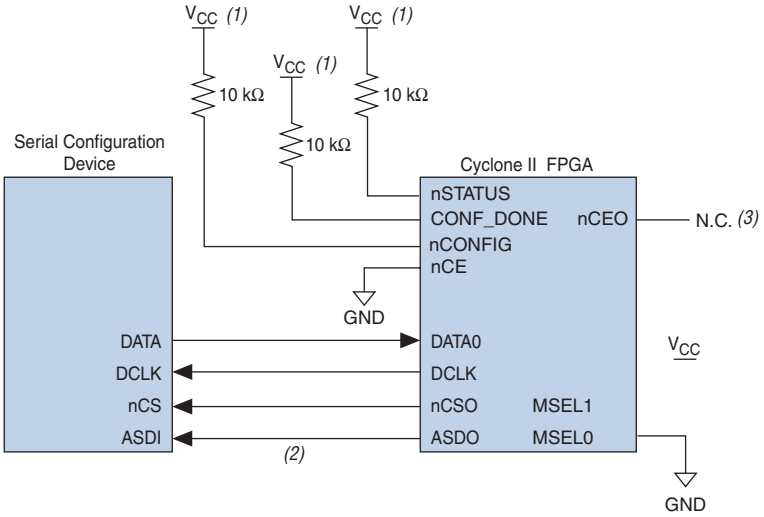
- Maintain equal distance between traces in LVDS pairs, as much as possible. Routing the pair of traces close to each other maximizes the common-mode rejection ratio (CMRR).
- Longer traces have more inductance and capacitance. These traces should be as short as possible to limit signal integrity issues.
- Place termination resistors as close to receiver input pins as possible.
- Use surface mount components.
- Avoid 90° or 45° corners.
- Use high-performance connectors.
- Design backplane and card traces so that trace impedance matches the connector's and/or the termination's impedance.
- Keep equal number of vias for both signal traces.
- Create equal trace lengths to avoid skew between signals. Unequal trace lengths result in misplaced crossing points and decrease system margins as the channel-to-channel skew (TCCS) value increases.
- Limit vias because they cause discontinuities.
- Use the common bypass capacitor values such as 0.001, 0.01, and 0.1 µF to decouple the high-speed PLL power and ground planes.
- Keep switching transistor-to-transistor logic (TTL) signals away from differential signals to avoid possible noise coupling.
- Do not route TTL clock signals to areas under or above the differential signals.
- Analyze system-level signals.

For PCB layout guidelines, see *AN 224: High-Speed Board Layout Guidelines*.

Conclusion

Cyclone II differential I/O capabilities enable you to keep pace with increasing design complexity. Support for I/O standards including LVDS, LVPECL, RSDS, mini-LVDS, differential SSTL and differential HSTL allows Cyclone II devices to fit into a wide variety of applications. Taking advantage of these I/O capabilities and Cyclone II pricing allows you to lower your design costs while remaining on the cutting edge of technology.

Figure 13–3. Single Device AS Configuration



Notes to Figure 13–3:

(1) Connect the pull-up resistors to a 3.3-V supply.

(2) Cyclone II devices use the ASDO to ASDI path to control the configuration device.

(3) The nCEO pin can be left unconnected or used as a user I/O pin when it does not feed another device's nCE pin.

Upon power-up, the Cyclone II device goes through a POR. During POR, the device resets, holds nSTATUS and CONF_DONE low, and tri-states all user I/O pins. After POR, which typically lasts 100 ms, the Cyclone II device releases nSTATUS and enters configuration mode when the external 10-kΩ resistor pulls the nSTATUS pin high. Once the FPGA successfully exits POR, all user I/O pins continue to be tri-stated. Cyclone II devices have weak pull-up resistors on the user I/O pins which are on before and during configuration.

The value of the weak pull-up resistors on the I/O pins that are on before and during configuration are available in the *DC Characteristics & Timing Specifications* chapter of the *Cyclone II Device Handbook*.

The configuration cycle consists of the reset, configuration, and initialization stages.

When designing a Cyclone II board for JTAG configuration, use the guidelines in Table 13–10 for the placement of the dedicated configuration pins.

Table 13–10. Dedicated Configuration Pin Connections During JTAG Configuration

Signal	Description
nCE	On all Cyclone II devices in the chain, nCE should be driven low by connecting it to ground, pulling it low via a resistor, or driving it by some control circuitry. For devices that are also in multiple device AS, or PS configuration chains, the nCE pins should be connected to GND during JTAG configuration or JTAG configured in the same order as the configuration chain.
nCEO	On all Cyclone II devices in the chain, nCEO can be used as a user I/O or connected to the nCE of the next device. If nCEO is connected to the nCE of the next device, the nCEO pin must be pulled high to V_{CCIO} by an external 10-kΩ pull-up resistor to help the internal weak pull-up resistor. If the nCEO pin is not connected to the nCE pin of the next device, you can use it as a user I/O pin after configuration.
MSEL	These pins must not be left floating. These pins support whichever non-JTAG configuration is used in production. If only JTAG configuration is used, you should tie these pins to ground.
nCONFIG	Driven high by connecting to V_{CC}, pulling up via a resistor, or driven high by some control circuitry.
nSTATUS	Pull to V_{CC} via a 10-kΩ resistor. When configuring multiple devices in the same JTAG chain, each nSTATUS pin should be pulled up to V_{CC} individually. nSTATUS pulling low in the middle of JTAG configuration indicates that an error has occurred.
CONF_DONE	Pull to V_{CC} via a 10-kΩ resistor. When configuring multiple devices in the same JTAG chain, each CONF_DONE pin should be pulled up to V_{CC} individually. CONF_DONE going high at the end of JTAG configuration indicates successful configuration.
DCLK	Should not be left floating. Drive low or high, whichever is more convenient on your board.

Figure 13–23 shows JTAG configuration of a Cyclone II device with a microprocessor.